

A

B

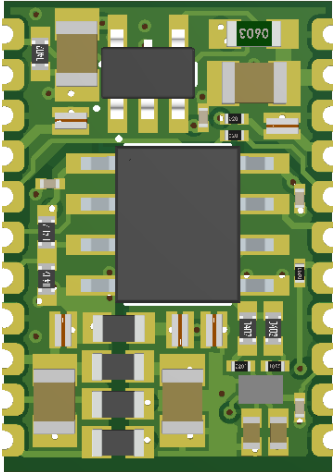
C

D

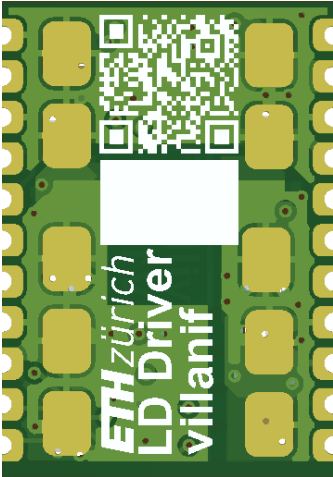
Layer Stack Legend

Material	Layer	Thickness	Type	Gerber	Weight
	Top Overlay		Legend	GTO	
	Surface Material	0.013mm	Solder Mask	GTS	
	Nickel, Gold	0.004mm	Surface Finish		
Copper	Top Layer	0.035mm	Signal	GTL	1oz
Prepreg		0.210mm	Dielectric		
Copper	Layer 1 (GND)	0.015mm	Signal	G1	0.5oz
Core		0.400mm	Dielectric		
Copper	Layer 2 (PWR)	0.015mm	Signal	G2	0.5oz
Prepreg		0.210mm	Dielectric		
Copper	Bottom Layer	0.035mm	Signal	GBL	1oz
Nickel, Gold	Bottom Surface Finish	0.004mm	Surface Finish		
Surface Material	Bottom Solder	0.013mm	Solder Mask	GBS	
	Bottom Overlay		Legend	GBO	
Total thickness: 0.955mm					

Realistic View



Realistic View



Eidgenössische Technische Hochschule Zürich
Swiss Federal Institute of Technology Zurich

Laboratory: IIS
Date: 17/07/2025 15:00
Rev: 1.0
Variation[No Variations]

File: PULSER_MAN.PCBDwf

Project: HELIOS-R
LD Pulser Driver - Manufacturing

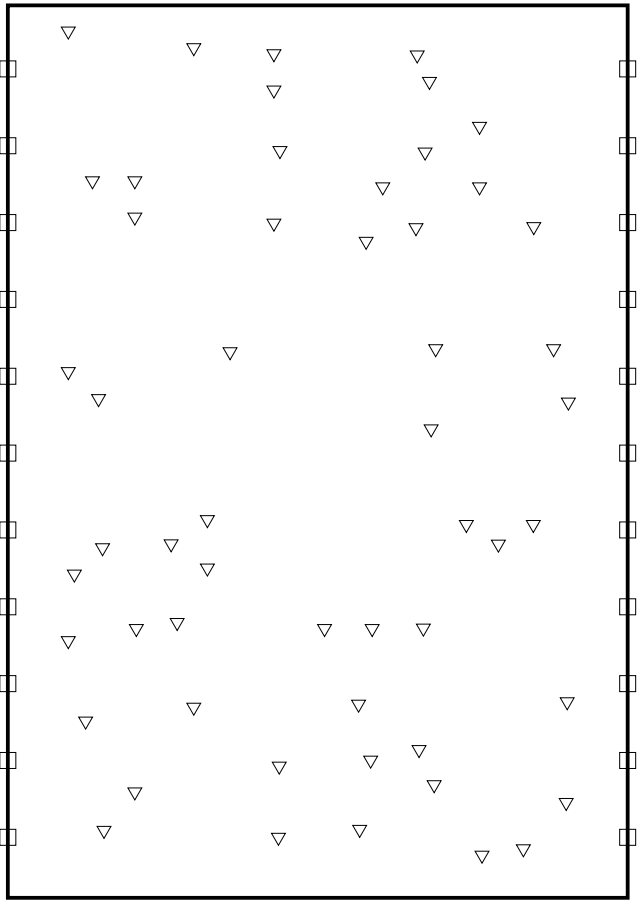
Drawn By: villanif
Checked By: *

A

B

C

D



Drill View vias top-bottom (Scale 8:1)

Drill Table - top to bottom

Symbol	Count	Hole Size	Plated	Drill Layer Pair	Via / Pad
▽	54	0.20mm	Plated	Top Layer - Bottom Layer	Via
□	22	0.60mm	Plated	Top Layer - Bottom Layer	Pad
	76 Total				